

L Number	Hits	Search Text	DB	Time stamp
1	1716	(glass near (lid cover substrate)) near3 plastic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/06 12:01
2	107	((glass near (lid cover substrate)) near3 plastic) and ((charge adj coupled adj device) ccd)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/06 12:03
3	19	(glass near lid) near3 plastic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/06 12:07
-	2	6133637.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/06 11:57
-	0	257/678,690,639,704	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/07 15:31
-	11564	(257/678-704).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/07 15:31
-	897010	((("257/678-704").CCLS.) and cover or lid or enclos\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/07 15:34
-	467	((("257/678-704").CCLS.) and 257/737	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/07 15:34
-	207098	((("257/678-704").CCLS.) and 257/737) and cover or lid	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/07 15:35
-	9	((("257/678-704").CCLS.) and 257/737) and plastic adj body	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/07 15:50
-	1	((("257/678-704").CCLS.) and 257/737) and plastic adj body and base	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/07 15:49
-	0	((("257/678-704").CCLS.) and 257/737) and plastic adj body and air adj gap	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/07 15:52

-	22854	(257/678-737).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/07 15:53
-	5723	((("257/678-737").CCLS.) and substrate and (cover or lead or enclose\$))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/07 15:54
-	6	(((((("257/678-737").CCLS.) and substrate and (cover or lead or enclose\$)) and lead and expose\$ adj portion) and air adj gap	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/07 15:56
-	2	(((((("257/678-737").CCLS.) and substrate and (cover or lead or enclose\$)) and lead and expose\$ adj portion) and plastic adj body	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/07 15:57
-	189	((("257/678-737").CCLS.) and substrate and (cover or lead or enclose\$)) and lead and expose\$ adj portion	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/07 16:27
-	1210	257/704	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/07 16:27
-	1	257/704 and bump and air adj gap	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/07 16:31
-	2	(257/704 and bump) and exposed adj portion same lead	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/07 16:32
-	118	257/704 and bump	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/07 16:47
-	0	5311402.pn	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/07 16:47
-	3	5188280.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/07 16:57
-	3	5311402.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/07 16:57